

**CoolMOS™ Power Transistor**
**Features**

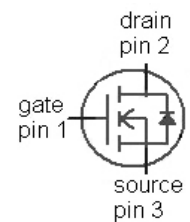
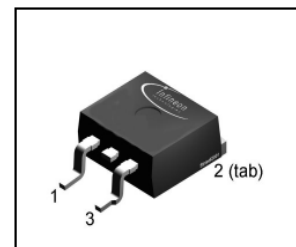
- Lowest figure-of-merit  $R_{ON} \times Q_g$
- Extreme dv/dt rated
- High peak current capability
- Qualified according to JEDEC<sup>1)</sup> for industrial applications
- Pb-free lead plating; RoHS compliant
- Ultra low gate charge

**CoolMOS™ 900V is designed for:**

- Quasi Resonant Flyback / Forward topologies
- SMPS
- PC Silverbox
- Lighting
- Solar

**Product Summary**

$V_{DS} @ T_J=25^\circ\text{C}$	900	V
$R_{DS(on),max} @ T_J=25^\circ\text{C}$	0.34	$\Omega$
$Q_{g,typ}$	94	nC

**PG-TO263**


Type	Package	Marking
IPB90R340C3	PG-TO263	9R340C

**Maximum ratings, at  $T_J=25^\circ\text{C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	$I_D$	$T_C=25^\circ\text{C}$	15	A
		$T_C=100^\circ\text{C}$	9.5	
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	$T_C=25^\circ\text{C}$	34	
Avalanche energy, single pulse	$E_{AS}$	$I_D=3.1\text{ A}, V_{DD}=50\text{ V}$	678	mJ
Avalanche energy, repetitive $t_{AR}$ <sup>2),3)</sup>	$E_{AR}$	$I_D=3.1\text{ A}, V_{DD}=50\text{ V}$	1	
Avalanche current, repetitive $t_{AR}$ <sup>2),3)</sup>	$I_{AR}$		3.1	A
MOSFET dv/dt ruggedness	dv/dt	$V_{DS}=0\dots400\text{ V}$	50	V/ns
Gate source voltage	$V_{GS}$	static	$\pm 20$	V
		AC ( $f>1\text{ Hz}$ )	$\pm 30$	
Power dissipation	$P_{tot}$	$T_C=25^\circ\text{C}$	208	W
Operating and storage temperature	$T_J, T_{stg}$		-55 ... 150	$^\circ\text{C}$

**Maximum ratings, at  $T_J=25\text{ °C}$ , unless otherwise specified**

Parameter	Symbol	Conditions	Value	Unit
Continuous diode forward current	$I_S$	$T_C=25\text{ °C}$	9.2	A
Diode pulse current <sup>2)</sup>	$I_{S,pulse}$		34	
Reverse diode $dv/dt$ <sup>4)</sup>	$dv/dt$		4	V/ns

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Thermal characteristics**

Thermal resistance, junction - case	$R_{thJC}$		-	-	0.6	K/W
Thermal resistance, junction - ambient	$R_{thJA}$	SMD version, device on PCB: at minimum footprint	-	-	62	K/W
	$R_{thJA}$	SMD version, device on PCB: at 6 cm <sup>2</sup> cooling area <sup>5)</sup>	-	35	-	
Soldering temperature, only reflow soldering allowed; part not qualified for direct wave soldering but bottom side PCB wave soldering is allowed	$T_{sold}$	reflow MSL1	-	-	260	°C

**Electrical characteristics, at  $T_J=25\text{ °C}$ , unless otherwise specified**
**Static characteristics**

Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS}=0\text{ V}$ , $I_D=250\text{ }\mu\text{A}$	900	-	-	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$ , $I_D=1\text{ mA}$	2.5	3	3.5	
Zero gate voltage drain current	$I_{DSS}$	$V_{DS}=900\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_J=25\text{ °C}$	-	-	2	$\mu\text{A}$
		$V_{DS}=900\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_J=150\text{ °C}$	-	20	-	
Gate-source leakage current	$I_{GSS}$	$V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$	-	-	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS}=10\text{ V}$ , $I_D=9.2\text{ A}$ , $T_J=25\text{ °C}$	-	0.28	0.34	$\Omega$
		$V_{GS}=10\text{ V}$ , $I_D=9.2\text{ A}$ , $T_J=150\text{ °C}$	-	0.76	-	
Gate resistance	$R_G$	$f=1\text{ MHz}$ , open drain	-	1.3	-	$\Omega$

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

**Dynamic characteristics**

Input capacitance	$C_{iss}$	$V_{GS}=0\text{ V}, V_{DS}=100\text{ V},$ $f=1\text{ MHz}$	-	2400	-	pF
Output capacitance	$C_{oss}$		-	120	-	
Effective output capacitance, energy related <sup>6)</sup>	$C_{o(er)}$	$V_{GS}=0\text{ V}, V_{DS}=0\text{ V}$ to 500 V	-	71	-	
Effective output capacitance, time related <sup>7)</sup>	$C_{o(tr)}$		-	280	-	
Turn-on delay time	$t_{d(on)}$	$V_{DD}=400\text{ V},$ $V_{GS}=10\text{ V}, I_D=9.2\text{ A},$ $R_G=23.1\ \Omega$	-	70	-	ns
Rise time	$t_r$		-	20	-	
Turn-off delay time	$t_{d(off)}$		-	400	-	
Fall time	$t_f$		-	25	-	

**Gate Charge Characteristics**

Gate to source charge	$Q_{gs}$	$V_{DD}=400\text{ V}, I_D=9.2\text{ A},$ $V_{GS}=0\text{ to }10\text{ V}$	-	11	-	nC
Gate to drain charge	$Q_{gd}$		-	41	-	
Gate charge total	$Q_g$		-	94	-	
Gate plateau voltage	$V_{plateau}$		-	4.6	-	V

**Reverse Diode**

Diode forward voltage	$V_{SD}$	$V_{GS}=0\text{ V}, I_F=9.2\text{ A},$ $T_J=25\text{ }^\circ\text{C}$	-	0.8	1.2	V
Reverse recovery time	$t_{rr}$	$V_R=400\text{ V}, I_F=I_S,$ $di_F/dt=100\text{ A}/\mu\text{s}$	-	510	-	ns
Reverse recovery charge	$Q_{rr}$		-	11	-	$\mu\text{C}$
Peak reverse recovery current	$I_{rrm}$		-	41	-	A

<sup>1)</sup> J-STD20 and JESD22

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{J,max}$ 
<sup>3)</sup> Repetitive avalanche causes additional power losses that can be calculated as  $P_{AV}=E_{AR} \cdot f$ .

<sup>4)</sup>  $I_{SD} \leq I_D$ ,  $di/dt \leq 200\text{ A}/\mu\text{s}$ ,  $V_{DClink}=400\text{ V}$ ,  $V_{peak} < V_{(BR)DSS}$ ,  $T_J < T_{J,max}$ , identical low side and high side switch

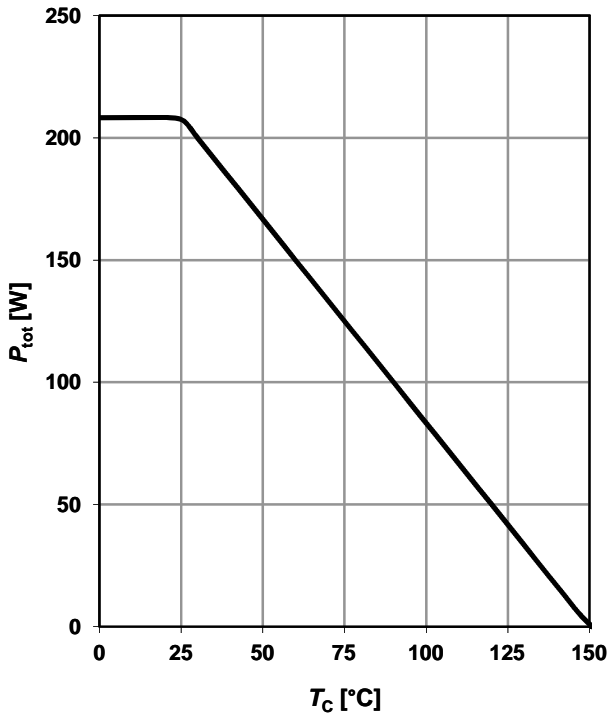
<sup>5)</sup> Device on 40mm\*40mm\*1.5mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 $\mu\text{m}$  thick) copper area for drain connection. PCB is vertical without blown air.

<sup>6)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 50%  $V_{DSS}$ .

<sup>7)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 50%  $V_{DSS}$ .

**1 Power dissipation**

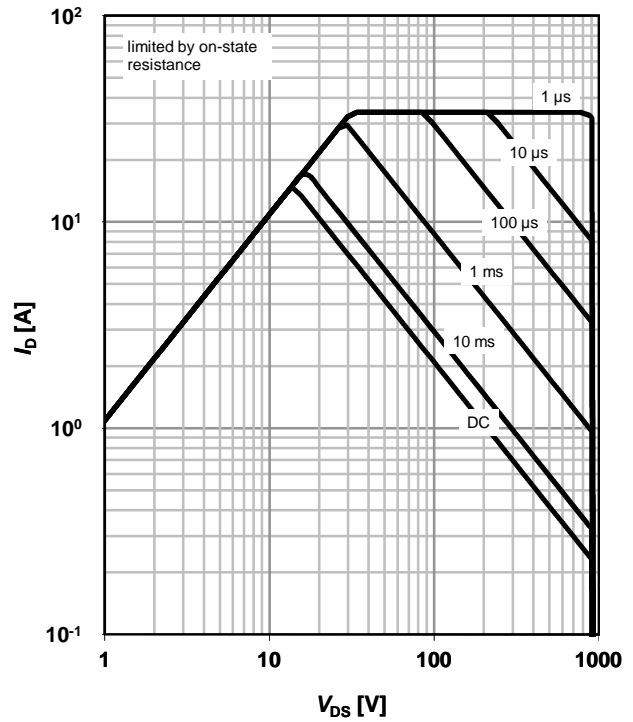
$P_{tot}=f(T_C)$



**2 Safe operating area**

$I_D=f(V_{DS}); T_C=25\text{ °C}; D=0$

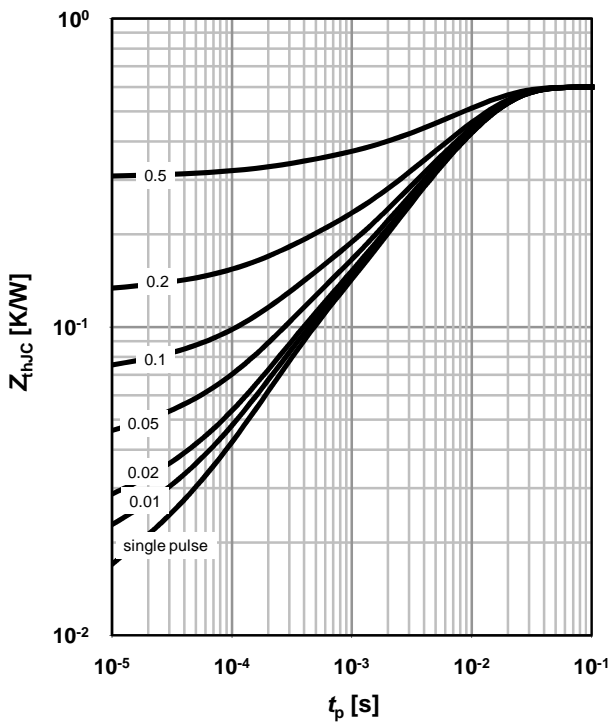
parameter:  $t_p$



**3 Max. transient thermal impedance**

$Z_{thJC}=f(t_p)$

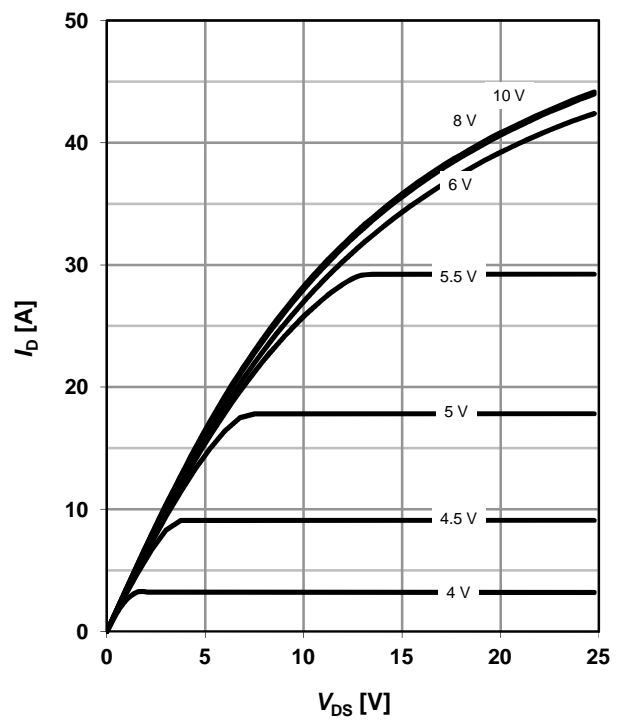
parameter:  $D=t_p/T$



**4 Typ. output characteristics**

$I_D=f(V_{DS}); T_J=25\text{ °C}$

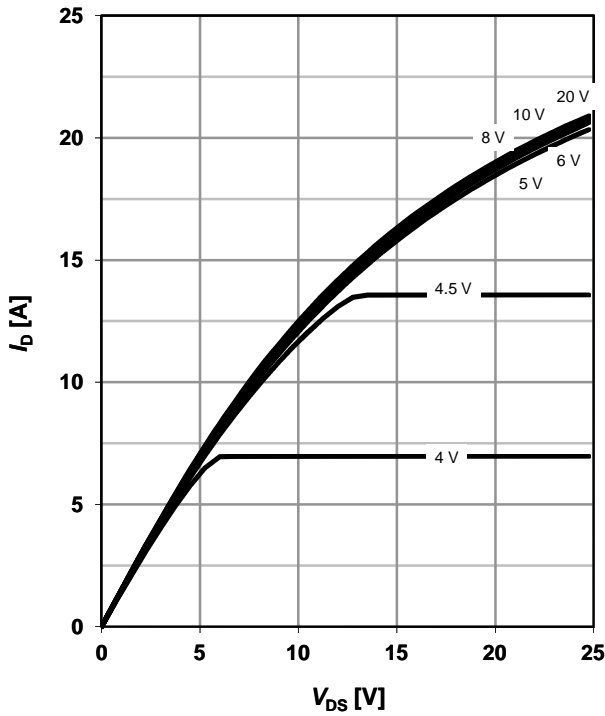
parameter:  $V_{GS}$



**5 Typ. output characteristics**

$I_D=f(V_{DS}); T_J=150\text{ }^\circ\text{C}$

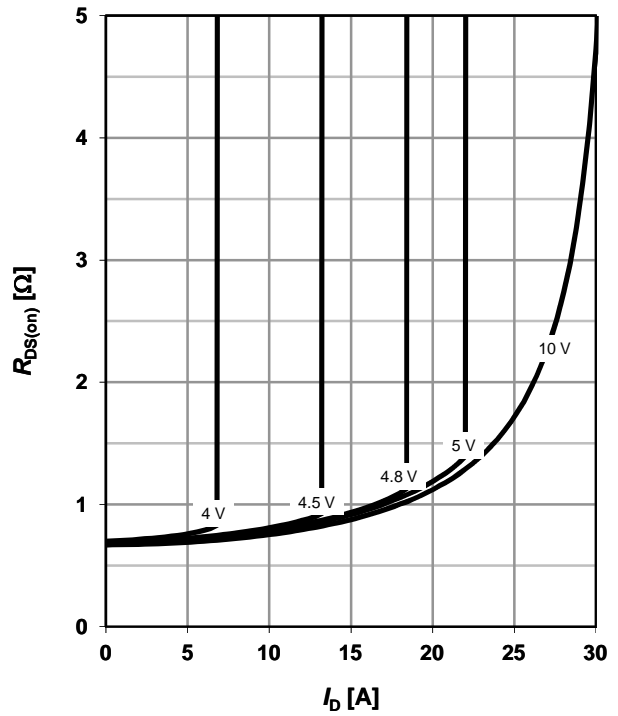
parameter:  $V_{GS}$



**6 Typ. drain-source on-state resistance**

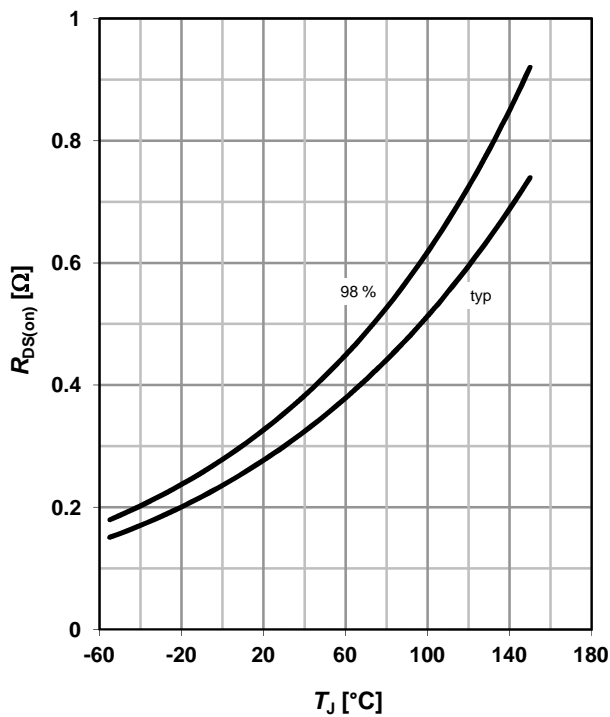
$R_{DS(on)}=f(I_D); T_J=150\text{ }^\circ\text{C}$

parameter:  $V_{GS}$



**7 Drain-source on-state resistance**

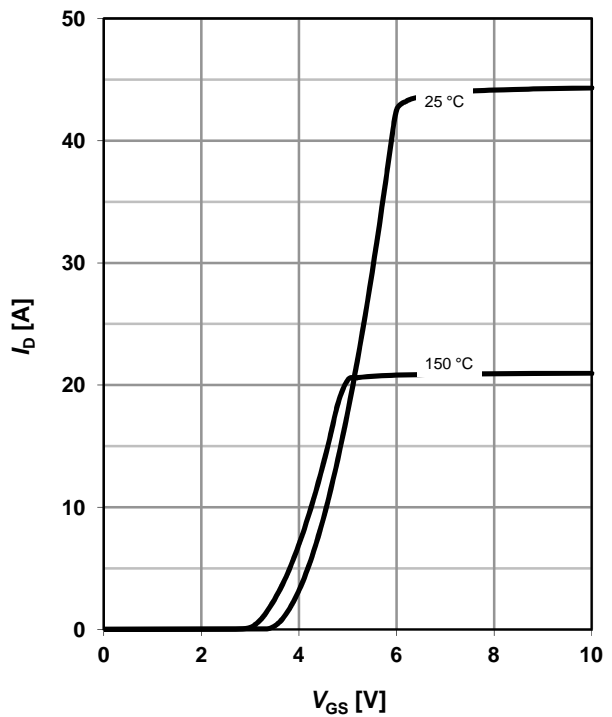
$R_{DS(on)}=f(T_J); I_D=9.2\text{ A}; V_{GS}=10\text{ V}$



**8 Typ. transfer characteristics**

$I_D=f(V_{GS}); V_{DS}=20\text{ V}$

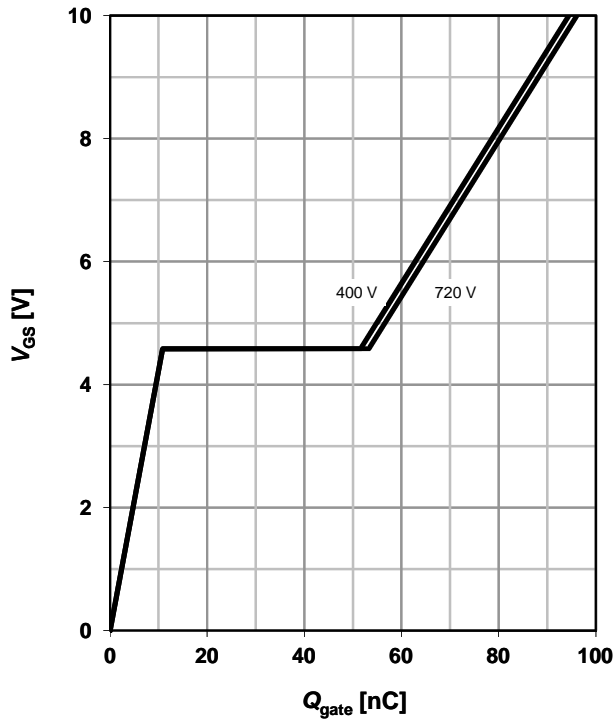
parameter:  $T_J$



**9 Typ. gate charge**

$V_{GS}=f(Q_{gate}); I_D=9.2\text{ A pulsed}$

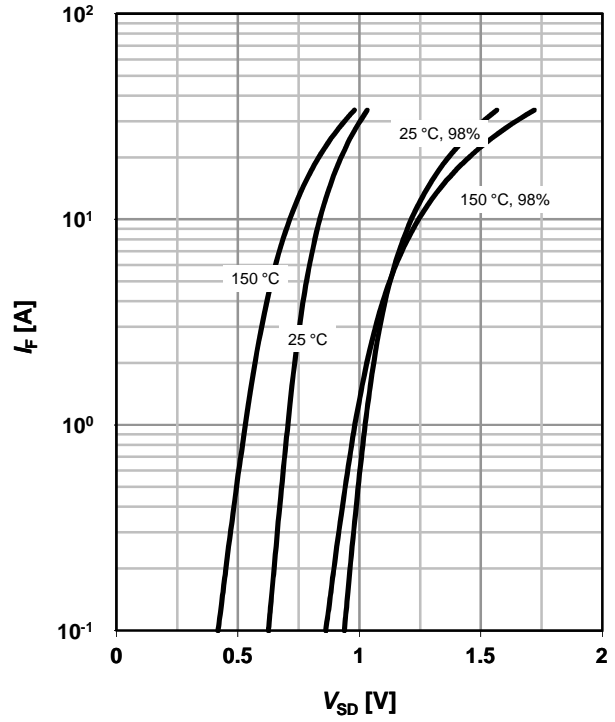
parameter:  $V_{DD}$



**10 Forward characteristics of reverse diode**

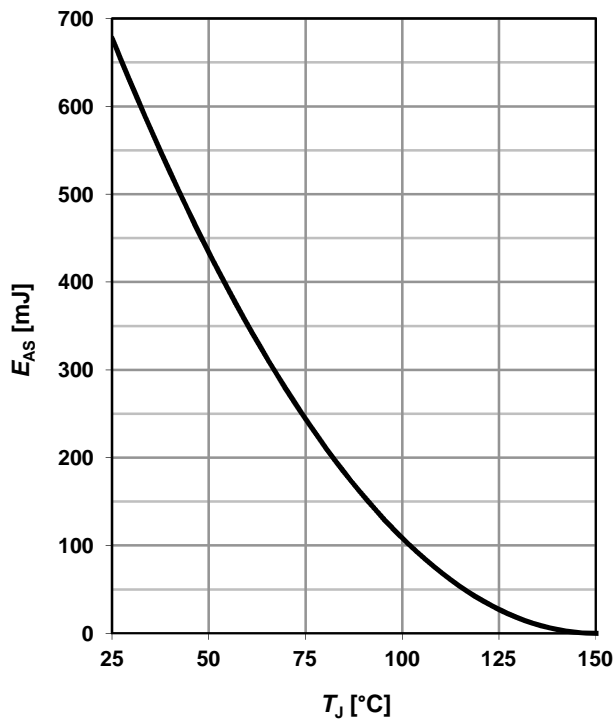
$I_F=f(V_{SD})$

parameter:  $T_J$



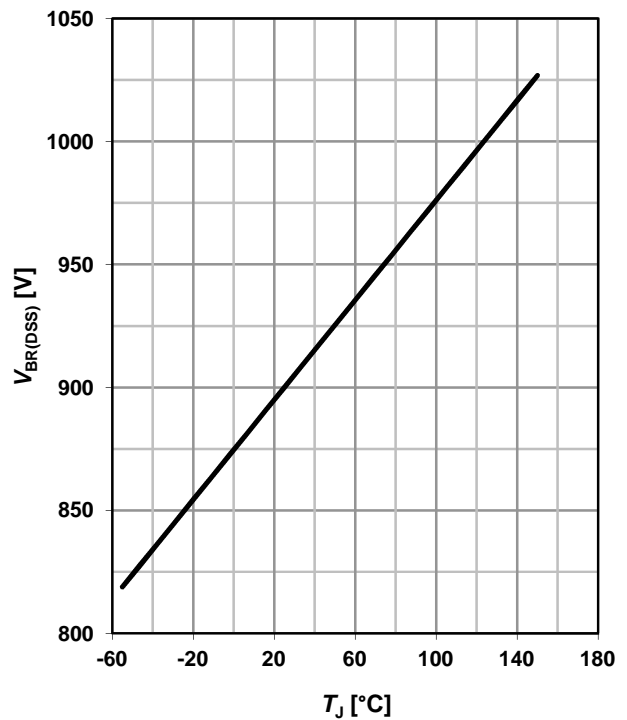
**11 Avalanche energy**

$E_{AS}=f(T_J); I_D=3.1\text{ A}; V_{DD}=50\text{ V}$



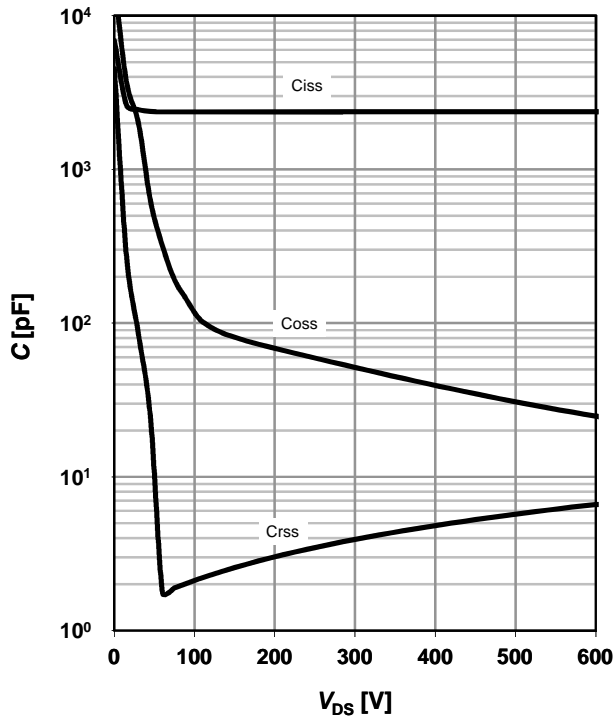
**12 Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_J); I_D=0.25\text{ mA}$



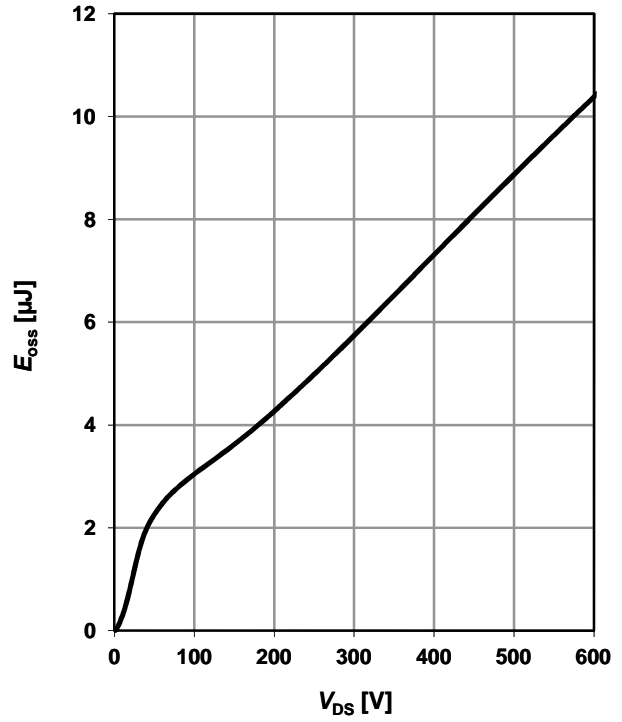
13 Typ. capacitances

$C=f(V_{DS}); V_{GS}=0\text{ V}; f=1\text{ MHz}$

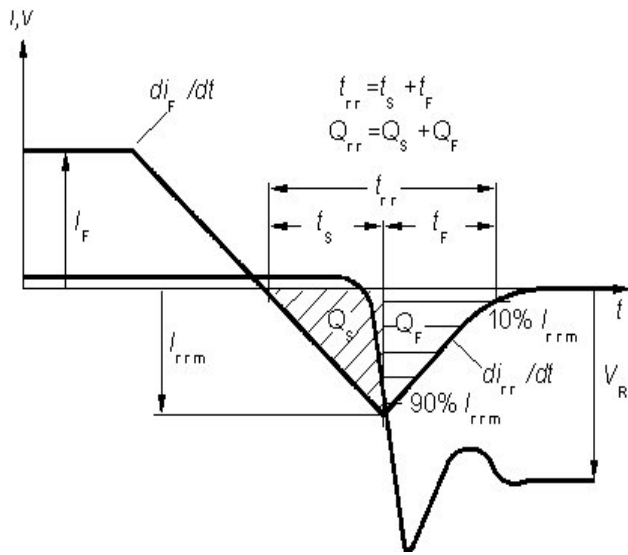


14 Typ. C<sub>oss</sub> stored energy

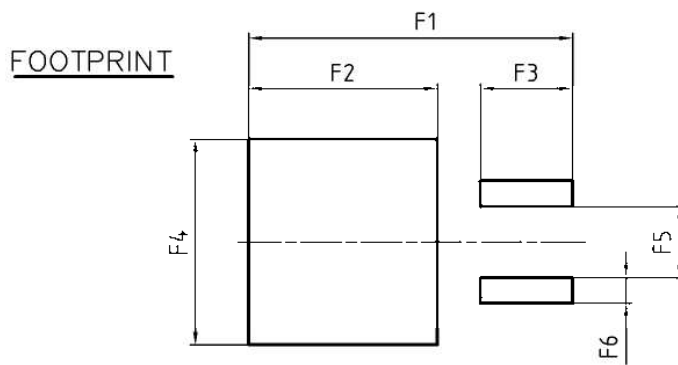
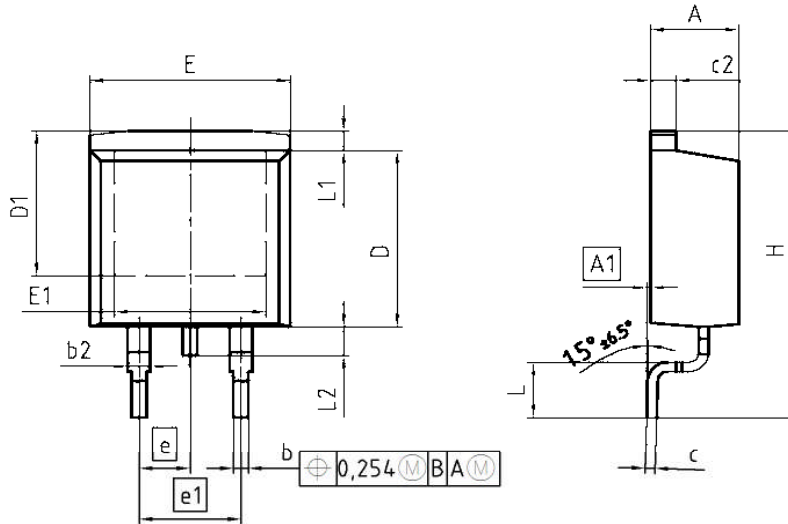
$E_{oss}=f(V_{DS})$



Definition of diode switching characteristics







DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.30	4.57	0.169	0.180
A1	0.00	0.25	0.000	0.010
b	0.65	0.85	0.026	0.033
b2	0.95	1.15	0.037	0.045
c	0.33	0.65	0.013	0.026
c2	1.17	1.40	0.046	0.055
D	8.51	9.45	0.335	0.372
D1	7.10	7.90	0.280	0.311
E	9.80	10.31	0.386	0.406
E1	6.50	8.60	0.256	0.339
e	2.54		0.100	
e1	5.08		0.200	
N	2		2	
H	14.61	15.88	0.575	0.625
L	2.29	3.00	0.090	0.118
L1	0.70	1.60	0.028	0.063
L2	1.00	1.78	0.039	0.070
F1	16.05	16.25	0.632	0.640
F2	9.30	9.50	0.366	0.374
F3	4.50	4.70	0.177	0.185
F4	10.70	10.90	0.421	0.429
F5	3.65	3.85	0.144	0.152
F6	1.25	1.45	0.049	0.057

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SCALE

7.5mm

EUROPEAN PROJECTION

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